

SG6841DZ

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Highly-Integrated Green-Mode PWM Controller

Qualification Data

Test Standards:

- ? Moisture Sensitivity: NA
- ? Thermal Impedance: 67/113
- ? Physical Dimensions: DIP

Attribute	Value	UOM
General Information		
Device Marking(TOP MARK)	SG6841DZ K&60&4&Z	
Family Code	0GD	
Package Type	DIP	
Package Description	008,PLASTIC, MOLDED DIP	
Pin Count	8	
Maximum Reflow Temperature	NA (thru hole)	
Restriction of Hazardous Substance		
Standard Plating Finish	Matte Sn	
Base Metal/Leadframe Material	Copper,Iron,Zinc,Phosphorus,Silver	
Lead Pitch	2540	
Minimum Lead Spacing	760	
Die Fabrication		
Fabrication Process Identifier	SG6841C	
Package Assembly*		
Plating Finish Layer Thickness	8.0um - 13um	
Thermal Impedance (Theta JA)	113	°C/Watt
Thermal Impedance (Theta JC)	67	°C/Watt
Moisture Sensitivity	NA	

*If an attribute is listed twice, either can be used on the part.